

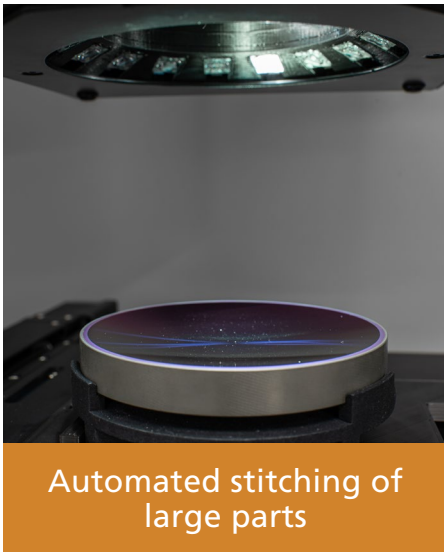
ARGOS matrix 200

automated scratch/dig inspection

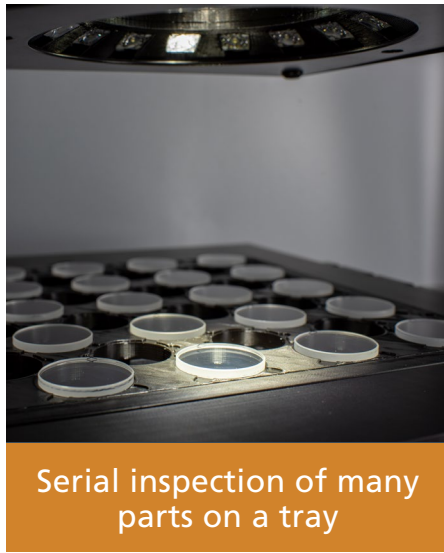
DI(O)PTIC
thinking your optics



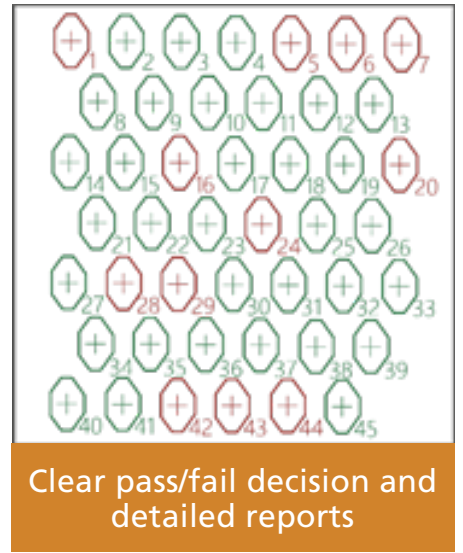
- FULLY AUTOMATED SURFACE INSPECTION
- VERSATILE FROM MICRO-OPTICS TO WAFERS
- OBJECTIVE AND REPRODUCIBLE



Automated stitching of large parts



Serial inspection of many parts on a tray



Clear pass/fail decision and detailed reports

BENEFITS

Large flexibility: any shape from aspheric micro lenses to 8" wafers can be inspected.

Automated serial inspection without user interaction reduces cost and improves process quality.

Objective test results with clear decisions and detailed information on relevant defects and statistics.

FUNCTIONALITY

ARGOS matrix 200 is equipped with a high-resolution camera and a switchable dark-field illumination. Images with different lighting configurations are fused for reliable defect detection with high repeatability. A precision 8" stage

allows inspection of large numbers of parts in a tray. Our stitching mode allows inspection of large parts - flat or curved. PDF test reports with clear decision and detailed information are automatically created.

SPECIFICATIONS

Parameter	ARGOS matrix 200
Nominal resolution (object-side pixel pitch)	2.5 µm
Maximum inspection area	205 x 205 mm
Smallest ISO 10110-7 size grade	0.004 (digs), 0.0025 (scratches)
Smallest visible defects*	< 1 µm
Precision of size measurement*	< 1.5 µm
Surface material	glass, metal, semiconductors, plastics
Inspection duration	7 min for 8" wafer
System size	ca. 700 x 600 x 600 mm

*for details see technical specification document